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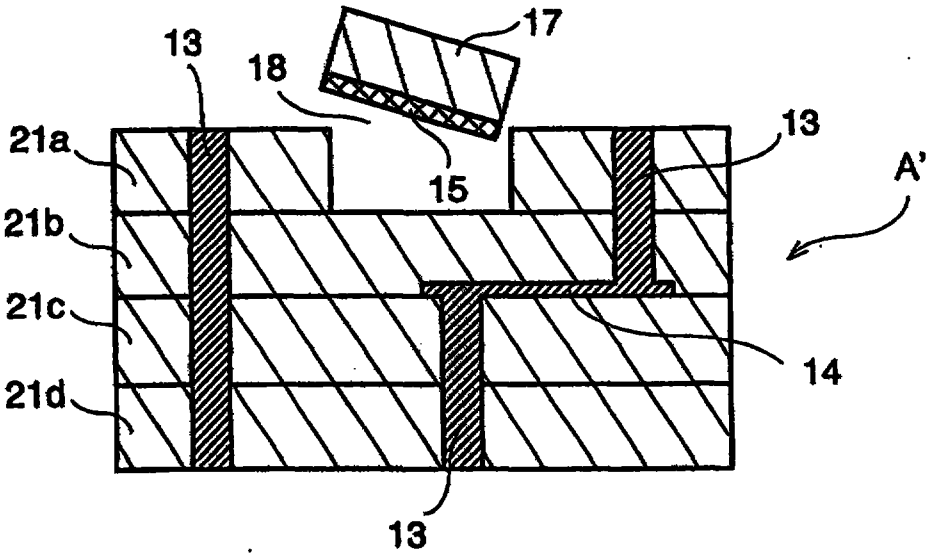
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(54) Title: METHOD OF MANUFACTURING A MULTI-LAYERED CERAMIC SUBSTRATE



(57) Abstract

A method of manufacturing a multi-layered ceramic substrate which does not require dies for making cavities, or aligning the green sheets. The method includes the steps of providing a plurality of green sheets having prefabricated via holes and wiring patterns therein; forming a layer for preventing sintering of adjacent green sheets at an area to become the bottom of the cavity; laminating and sintering the green sheets to create a multi-layered sintered body; and making a cut along the inner wall of the cavity all the way to the bottom of the cavity and removing the inside sintered portion leaving the formed cavity. This method eliminates the need for expensive dies, thus providing a simple, stable, and inexpensive manufacturing method for a multi-layered ceramic substrate.